

Electronic Patent Application Fee Transmittal

Application Number:	10824035			
Filing Date:	14-Apr-2004			
Title of Invention:	BONDING PAD STRUCTURE AND METHOD OF FORMING THE SAME			
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Filer:	Daniel R. McClure/Hui Chin Barnhill			
Attorney Docket Number:	252011-2220			
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Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1400	1400
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Total in USD (\$)				1700